

LIST 13 (See S.No.184 of the Table)

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| (1) LSI / VLSI tester | (14) Lithography systems | (26) Wafer sawing machine; Wafer prober |
| (2) Micromanipulators | (15) Direct step on wafers / steppers | (27) Leak detection system |
| (3) Molecular beam epitaxy system (MBE system) | (16) X-ray lithography systems | (28) Clean room air showers |
| (4) Epitaxial reactors | (17) E-Beam mask making system | (29) Particle monitor / counter both air and liquid borne |
| (5) Chemical vapour deposition (CVD) system - Low pressure CVD (LP CVD) - Metal organic CVD (MO CVD) | (18) E-Beam direct write system | (30) Automatic encapsulation system; Automatic marking / branding machine |
| (6) High pressure oxidation systems | (19) Mask aligners | (31) Clean room laminar flow air handling system |
| (7) Chemical etching systems | (20) Mask inspection systems (comparators) | (32) Ultra clean room equipment |
| (8) Plasma etchers | (21) Tape automated bonders | (33) Ultra high purity demineralised water treatment plant |
| (9) Reactive ion beam etchers (RIBE) | (22) Laser zappers | (34) PVDF welding and orbital welding machines |
| (10) Reactive ion etchers | (23) Wafer recognition wire bonders | (35) Ultra high pure (UHP) gas distribution system |
| (11) RF sputtering systems | (24) Wafer scribe or Wafer slicer or Wafer sawing machine or Wafer fractures or any combination thereof | (36) Toxic gas distribution / monitoring system |
| (12) Direct digital control furnaces | (25) Die bonders or wire bonders or combination thereof | |
| (13) Ion-implanters (low/ medium / high current) | | |